

ABSTRACT

ADHESIVE TAPE COMPOSITION FOR ELECTRONIC COMPONENTS

The present invention pertains to an adhesive tape composition for
5 electronic components used for bonding electronic components used in
semiconductor devices, e.g., leads, PRH, semiconductor chips, die pads,
etc. In particular, the present invention concerns an adhesive tape
composition excellent in electric reliability, adhesive strength and taping
workability.

10 The adhesive tape composition according to the present invention is
characterized in that it contains acrylonitrile butadiene rubber (NBR)
containing the carboxyl functional group at the end thereof, epoxy resin,
phenol resin and one or more sorts of hardener selected from amine and
acid anhydride hardeners.

15 **(Fig. 1)**